

Document	Number	Description	Type	Date
-	259	encapsulated) near2 thickness (((sealing adj resin) encapsulating encapsulated) near2 thickness) and (chip device die)	USPAT	2000/11/30 13:40
-	48	(((sealing adj rcsin) encapsulating encapsulated) near2 thickness) near5 (chip device die)	USPAT	2001/06/14 08:23
-	4	((("5844168") or ("5642261") or ("5525834") or ("5683942")) .PN.	USPAT	2000/11/30 15:30
-	0	((("4996587") or ("5672909") or ("5796170")) .PN.	USPAT	2000/11/30 15:30
-	1410	257/723	USPAT	2000/12/01 16:32
-	1142	257/724	USPAT	2000/12/01 16:32
-	1865	257/723 257/724	USPAT	2000/12/01 16:32
-	881	(257/723 257/724) and lead and substrate	USPAT	2000/12/01 16:33
-	139	((257/723 257/724) and lead and substrate) and multichip	USPAT	2000/12/01 16:44
-	135	((257/723 257/724) and lead and substrate) and (chip near1 chip)	USPAT	2000/12/01 16:45
-	94	(((257/723 257/724) and lead and substrate) and (chip near1 chip)) not (((257/723 257/724) and lead and substrate) and multichip)	USPAT	2000/12/01 16:46
-	3	(multichip near1 package) and ((flexible near (substrate tape insulation)) with (conductive near trace))	USPAT; EPO; JPO; DERWENT	2001/06/14 08:32
-	81	((sealing adj resin) encapsula\$4) near2 thickness) near5 (chip device die)	USPAT	2001/06/14 08:25
-	95	((sealing adj resin) encapsula\$4) near2 thickness) near5 (chip device die)	USPAT; US-PGPUB; EPO; JPO	2001/06/14 08:26
-	1	(((sealing adj resin) encapsula\$4) near2 thickness) near5 (chip device die)) and (flexible near1 (lead trace conductive))	USPAT; US-PGPUB; EPO; JPO	2001/06/14 08:29
-	4	(multichip near1 package) and ((flexible near (substrate tape insulation)) with (conductive near trace))	USPAT; EPO; JPO; DERWENT	2001/06/14 08:33
-	71	(second near1 chip) with (heat near2 (conducting releasing radiator sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 13:39
-	82	(second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 15:02
-	1	6156980.URPN.	USPAT	2002/05/14 13:51
-	5	("5352926" "5710071" "5777386" "5969461" "5973927") .PN.	USPAT	2002/05/14 13:51
-	1	"5086431" .PN.	USPAT	2002/05/14 14:10
-	2	5638391.URPN.	USPAT	2002/05/14 14:11
-	22	5323292.URPN.	USPAT	2002/05/14 14:16
-	40	("3324224" "4313492" "4335781" "4480262" "4561040" "4603374" "4727455" "4740866" "4806503" "4825284" "4888449" "4897508" "4912548" "4939316" "4949219" "4961106" "4967260" "5015803" "5018005" "5023398" "5025114" "5055967" "5066368" "5073521" "5103292" "5175613" "5184211" "5189505" "5214308" "5216283" "5235209" "5256205" "5284706" "5291064" "5323292" "5324569" "5334857" "5352926" "5353193"	USPAT	2002/05/14 14:44

Line No.	Text	Text	Text	Text	Text	Text
41	"5040052"	"5140404"	"5172215"			
	"5176311"	"5177032"	"5198888"			
	"5291060"	"5291061"	"5323060"			
	"5384689"	"5432729"	"5620928"			
	"5682062"	"5721452"	"5739581"			
	"5815372"	"5872025"	"5886412"			
	"5989982"	"6013948"	"6030855"			
	"RE36613"	"6033931"	"6049094"			
	"6051886"	"6057598"	"6087722"			
	"6133637"	"6201302"	"6204091"			
	"6215182"	"6229217") .PN.				
187	(second adj chip) and (heat near2 (conducting conductive release releasing radiator sink))			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 15:01	
165	((second adj chip) and (heat near2 (conducting conductive release releasing radiator sink)) not ((second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink))))			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 15:02	
112	((second adj chip) and (heat near2 (conducting conductive release releasing radiator sink)) not ((second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink)))) and (wire wiring)			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 15:56	
2	("5866949" "5925934") .PN.			USPAT	2002/05/14 15:09	
0	6201266.URPN.			USPAT	2002/05/14 15:09	
16	5199165.URPN.			USPAT	2002/05/14 15:19	
16	5199165.URPN.			USPAT	2002/05/14 15:22	
13	("2350348" "3361195" "3564109" "4047198" "4327399" "4519447" "4631636" "4727454" "4859520" "4878152" "4967314" "4994215" "5095359") .PN.			USPAT	2002/05/14 15:22	
37	4862322.URPN.			USPAT	2002/05/14 15:26	
41	5438224.URPN.			USPAT	2002/05/14 15:40	
0	6313527.URPN.			USPAT	2002/05/14 15:41	
2	("5438224" "6072243") .PN.			USPAT	2002/05/14 15:41	
3	6137164.URPN.			USPAT	2002/05/14 15:44	
15	("3577037" "5347162" "5438224" "5468681" "5477160" "5483421" "5759047" "5786628" "5815374" "5918113" "5958590" "5965064" "5977640" "5984691" "6013948") .PN.			USPAT	2002/05/14 15:45	
53	((second adj chip) and (heat near2 (conducting conductive release releasing radiator sink)) not ((second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink)))) not (((second adj chip) and (heat near2 (conducting conductive release releasing radiator sink)) not ((second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink)))) and (wire wiring))			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 16:01	
1570	noise near shield\$3			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 16:03	
0	257/685,686,723,724,777			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 16:05	

4	("5677575" "5757078" "5821625" "5869903").PN. 6 5821625.URPN. 6 5821625.URPN.	USPAT; EPO; JPO; DERWENT USPAT	2002/05/14 16:07
5	("4763188" "4811082" "5508565" "5596225" "5656856").PN.	USPAT	2002/05/14 16:08
6	(noise near shield\$3) and ((chip adj1 chip) (dual adj dies adj packag\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/14 16:11
6	((noise near shield\$3) and ((chip adj1 chip) (dual adj dies adj packag\$3))) not ((noise near shield\$3) and 257/685,686,723,724,777.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/14 16:19
5	(noise near shield\$3) and (stacked with (chip semiconductor (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/14 16:20
2	(aln (aluminum adj nitride)) near3 (solder adj (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/28 13:58
41	(aln (aluminum adj nitride)) near3 (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/28 13:59
8	((solder adj (bump ball)) near2 copper) and ((wiring adj layer) near2 copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/29 10:10
13	(lcad near2 copper) and ((wiring adj layer) ncar2 copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/29 10:12
21	(electrode near2 copper) and ((wiring adj layer) near2 copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/29 10:12
60	"5477082"	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/29 12:27
47	"5438224"	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/29 12:27
15	"4703483"	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/29 12:32
11	"5719436"	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/29 12:34
129	"5477082" "5438224" "4703483" "5719436"	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2002/05/29 12:34
7	("5065505" "5396403" "5477082" "5977640" "6075287" "6133637" "6150724").PN.	USPAT	2002/05/29 12:39
11	("5471369" "5646829" "5719436" "5757078" "5821625" "5869903" "5977640" "6075287" "6133637" "6150724").PN.	USPAT	2002/05/29 12:42

Number	Description	Office	Priority
6	"5205035" "5208729" "5238176" "5243141" "5244833" "5252857" "5268815").PN.	USPAT	2002/05/29 13:02
1	5821625.URPN.	USPAT	2002/10/10 09:17
4	("5677575" "5757078" "5821625" "5869903").PN.	USPAT	2002/10/10 09:17
6	5821625.URPN.	USPAT	2002/10/10 09:18
5	("4763188" "4811082" "5508565" "5596225" "5656856").PN.	USPAT	2002/10/10 09:18
32779	chip adj2 chip) (second adj1 chip	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:47
70	(chip adj2 chip) (second adj1 chip) and ((digital analog) near cell)	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:52
5	((chip adj2 chip) (second adj1 chip) and ((digital analog) near cell)) and ((bond bonding) adj pad)	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:53
3106	(digital analog) near1 cell	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:38
14	((digital analog) near cell) and (second near1 (die chip))	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:45
8	((digital analog) near cell) and (first near1 (die chip))	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:46
41933	(chip near2 chip) (second near1 (die chip))	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:50
38050	(chip near2 chip) ((second adj (die chip)) (second adj1 (die chip)))	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:52
1529	((chip near2 chip) ((second adj (die chip)) (second adj1 (die chip)))) and digital and analog and cell	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:53
215	((chip near2 chip) ((second adj (die chip)) (second adj1 (die chip)))) and digital and analog and cell) and ((bond bonding) adj pad)	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:53
179	((((chip near2 chip) ((second adj (die chip)) (second adj1 (die chip)))) and digital and analog and cell) and ((bond bonding) adj pad)) and (wire wiring)	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:54
177	(((((chip near2 chip) ((second adj (die chip)) (second adj1 (die chip)))) and digital and analog and cell) and ((bond bonding) adj pad)) and (wire wiring)) and circuit	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:55
120	((((((chip near2 chip) ((second adj (die chip)) (second adj1 (die chip)))) and digital and analog and cell) and ((bond bonding) adj pad)) and (wire wiring)) and circuit) and claim	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2002/10/10 09:55

		"5923091" "5946545" "5995379" "6057598").PN.		
18	6057598.URPN.		USPAT	2002/10/10 13:19
8	("5294826" "5341979" "5367765" "5506756" "5532512" "5610442" "5724230" "5786635").PN.		USPAT	2002/10/10 13:23
10	("5243208" "5386623" "5717245" "5783870" "5894166" "5923090" "5923091" "5946545" "5995379" "6057598").PN.		USPAT	2002/10/10 13:28
2	6255736.URPN.		USPAT	2002/10/10 13:28
6	("4764804" "5034345" "5480834" "5534465" "5585282" "5726500").PN.		USPAT	2002/10/10 13:29
3106	(digital analog) near cell	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:43	
21	((digital analog) near cell) near3 (chip dram)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:44	
48	((digital logic) near cell) with (analog near cell)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:32	
5	((digital logic) near cell) with (analog near cell)) with (chip dram)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:26	
0	6460172.URPN.	USPAT	2002/10/10 13:48	
11	("4402044" "5197016" "5361373" "5384275" "5402358" "5425036" "5438681" "5581742" "5959871" "6006022" "6014509").PN.	USPAT	2002/10/10 13:48	
9138	(multichip adj module) mcm	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:48	
25628	(digital logic input output analog) near cell	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:46	
104	((multichip adj module) mcm) and ((digital logic input output analog) near cell)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:35	
103	((multichip adj module) mcm) and ((digital logic input output analog) near cell) not ("6054337" "5894166" "5898223" "6147401" "6414396")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:36	
43	((multichip adj module) mcm) and ((digital logic input output analog) near cell) not ("6054337" "5894166" "5898223" "6147401" "6414396")) and (wire wiring) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:36	
7794	(digital logic analog) near1 cell	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:47	
14778	(multichip adj module) mcm (second near1 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 16:02	
106	((digital logic analog) near1 cell) and	USPAT	2002/10/10 14:50	

			US PAT; EPO; JPO; DERWENT	
		((multichip adj module) mcm (second near1 chip)) not (((multichip adj module) mcm) and ((digital logic input output analog) near cell))		
-	73	((digital logic analog) near1 cell) and ((multichip adj module) mcm (second near1 chip)) and (ram dram)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 15:28
-	36	(((digital logic analog) near1 cell) and ((multichip adj module) mcm (second near1 chip)) and (ram dram)) not (((digital logic analog) near1 cell) and ((multichip adj module) mcm (second near1 chip))) not ((multichip adj module) mcm) and ((digital logic input output analog) near cell))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 15:28
-	48	(US-6137164-\$ or US-5793115-\$ or US-4862322-\$ or US-6344683-\$ or US-6156980-\$ or US-5533256-\$ or US-5638391-\$ or US-5323292-\$ or US-6052284-\$ or US-5608610-\$ or US-5578869-\$ or US-5214308-\$ or US-6340842-\$ or US-6201302-\$ or US-6225688-\$ or US-6201266-\$ or US-5199165-\$ or US-4774632-\$ or US-6292366-\$ or US-6069025-\$ or US-5539250-\$ or US-5438224-\$ or US-6313527-\$ or US-6080931-\$ or US-6072243-\$ or US-6232668-\$).did. or (US-5821625-\$ or US-6285076-\$ or US-6020867-\$ or US-5668040-\$ or US-6376917-\$ or US-6316822-\$ or US-5719436-\$ or US-5477082-\$ or US-6433398-\$ or US-6373447-\$ or US-6356958-\$ or US-6308143-\$ or US-6255736-\$ or US-6057598-\$ or US-5386623-\$ or US-5243208-\$ or US-6202183-\$ or US-6460172-\$).did. or (US-20020033526-\$ or US-20020130342-\$ or US-20020078278-\$ or US-20020006054-\$).did.	USPAT; US-PGPUB	2002/10/10 15:33
-	13	("4484292" "5222293" "5249134" "5251147" "5267176" "5381343" "5471398" "5481473" "5613102" "5638293" "5666288" "5712794" "5901066").PN.	USPAT	2002/10/10 15:39
-	7	5793115.URPN.	USPAT	2002/10/10 15:44
-	1	6208545.URPN.	USPAT	2002/10/10 15:45
-	32	("4070230" "4131985" "4416064" "4539068" "4585991" "4612083" "4617160" "4618397" "4618763" "4702936" "4706166" "4721938" "4761681" "4784721" "5070026" "5071510" "5130894" "5236118" "5262351" "5273940" "5284796" "5385632" "5424920" "5426072" "5432729" "5457879" "5502667" "5534466" "5581498" "5637536" "5760478" "5793115").PN.	USPAT	2002/10/10 15:46
-	14778	((multichip adj module) mcm) (second near1 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 16:09
-	59	(circuit adj area) near3 ((bond bonding) adj pad)	USPAT; US-PGPUB; EPO; JPO;	2002/10/10 16:10

		multichip adj module adj pad;	USPAT; EPO; JPO; DERWENT	2002/10/10 16:11
-	2	((circuit adj area) near3 ((bond bonding) adj pad)) and (((multichip adj module) mcm) (second near1 chip)) and (mother adj chip))	USPAT; EPO; JPO; DERWENT	2002/10/10 16:12
-	26	((multichip adj module) mcm) (second near1 chip)) and (mother adj chip)	USPAT; EPO; JPO; DERWENT	2002/10/10 16:13
-	0	20020017718.URPN.	USPAT	2002/10/10 16:14
-	6	("4697095" "5440423" "5640107" "5801547" "5977640" "6049222").PN.	USPAT	2002/10/10 16:15
-	24	4697095.URPN.	USPAT	2002/10/10 16:16
-	5	5446309.URPN.	USPAT	2002/10/10 16:20
-	3	("4697095" "4890077" "5008736").PN.	USPAT	2002/10/10 16:21
-	9	("4055754" "4071902" "4103182" "4350906" "4446390" "4509008" "4550289" "4558447" "4612499").PN.	USPAT	2002/10/10 16:21
-	23	("5072364" "5142634" "5230068" "5287467" "5303356" "5394529" "5428786" "5454117" "5469551" "5508556" "5564118" "5592634" "5623614" "5630157" "5732278" "5760478" "5834835" "5856937" "5903908" "5939782" "5977640" "5994166" "6031284").PN.	USPAT	2002/10/10 16:22